

### Features

- Guard Ring Die Construction for Transient Protection
- Ideally Suited for Automated Assembly
- Low Power Loss, High Efficiency
- Surge Overload Rating to 30A Peak
- For Use in Low Voltage, High Frequency Inverters, Free Wheeling, and Polarity Protection Application
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Notes 3 & 4)
- Qualified to AEC-Q101 Standards for High Reliability

## **Mechanical Data**

- Case: SMA/SMB
- Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Lead Free Plating (Matte Tin Finish). Solderable per MIL-STD-202, Method 208 (63)
- Polarity: Cathode Band or Cathode Notch
  - Weight: SMA 0.064 grams (approximate) SMB 0.093 grams (approximate)



Top View



Bottom View

## Ordering Information (Note 5)

Part Number	Qualification	Case	Packaging
B1XX-13-F	Commercial	SMA	5000/Tape & Reel
B140Q-13-F	Automotive	SMA	5000/Tape & Reel
B150Q-13-F	Automotive	SMA	5000/Tape & Reel
B1XXB-13-F	Commercial	SMB	3000/Tape & Reel

\*xx = Device Type, e.g. B120-13-F (SMA Package); B120B-13-F (SMB Package).

1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.

2. See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

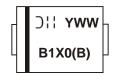
3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. Product manufactured with Date Code 0924 (week 24, 2009) and newer are built with Green Molding Compound.

5. For packaging details, go to our website at http://www.diodes.com/products/packages.html

## **Marking Information**

Notes:



B1X0 = Product type marking code, ex: B120 (SMA package) B1X0B = Product type marking code, ex: B160B (SMB package) C|| = Manufacturers' code marking YWW = Date code marking Y = Last digit of year (ex: 2 for 2002) WW = Week code (01 to 53)



## Maximum Ratings (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load

Characteristic	Symbol	B120/B	B130/B	B140/B	B150/B	B160/B	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V <sub>RRM</sub> V <sub>RWM</sub> VR	20	30	40	50	60	V
RMS Reverse Voltage	V <sub>R(RMS)</sub>	14	21	28	35	42	V
Average Rectified Output Current @ T <sub>T</sub> = +130°C		1.0					А
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load			A				

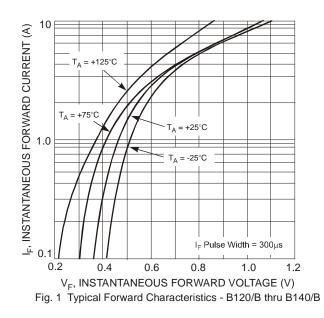
## **Thermal Characteristics**

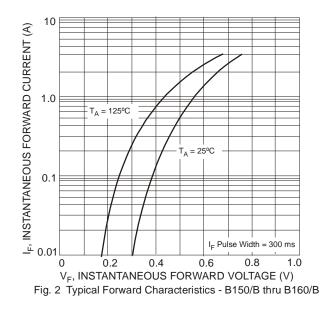
Characteristic	Symbol	B120/B	B130/B	B140/B	B150/B	B160/B	Unit
Typical Thermal Resistance Junction to Terminal (Note 6) R <sub>θJT</sub> 20			°C/W				
perating and Storage Temperature Range T <sub>J</sub> , T <sub>STG</sub> -65 to +150			°C				

### Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Chara	cteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Forward Voltage Drop	B120/B, B130/B, B140/B B150/B, B160/B				0.5 0.7	V	I <sub>F</sub> = 1.0A I <sub>F</sub> = 1.0A
Leakage Current (Note 7)		I <sub>R</sub>	-	-	0.5 10		@ Rated $V_{R}$ , $T_{A} = +25^{\circ}C$ @ Rated $V_{R}$ , $T_{A} = +100^{\circ}C$
Total Capacitance		CT	-	-	110	pF	$V_R = 4V, f = 1MHz$

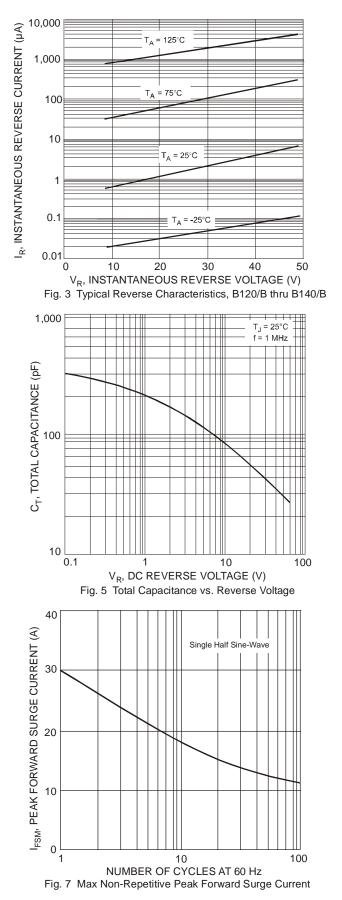
Notes: 6. Thermal Resistance: Junction to terminal, unit mounted on PC board with 5.0 mm<sup>2</sup> (0.013 mm thick) copper pads as heat sink. 7. Short duration pulse test used to minimize self-heating effect.

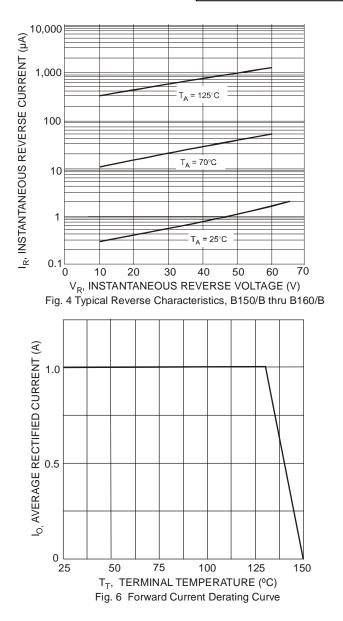






# B120/B - B160/B

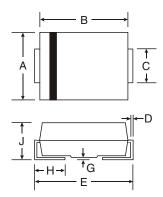






# **Package Outline Dimensions**

Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.

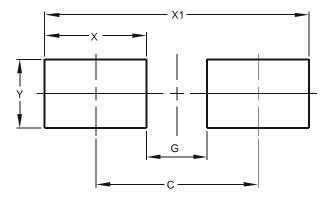


SMA						
Dim	Min	Max				
Α	2.29	2.92				
В	4.00	4.60				
с	1.27	1.63				
D	0.15	0.31				
ш	4.80	5.59				
G	0.05	0.20				
H	0.76	1.52				
J	2.01	2.30				
All Dimensions in mm						

SMB						
Dim	Min	Max				
Α	3.30	3.94				
В	4.06	4.57				
С	1.96	2.21				
D	0.15	0.31				
ш	5.00	5.59				
G	0.05	0.20				
H	0.76	1.52				
J	2.00	2.50				
All Dimensions in mm						

## Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	SMA (in mm)	SMB (in mm)		
С	4.00	4.30		
G	1.50	1.80		
Х	2.50	2.50		
X1	6.50	6.80		
Y	1.70	2.30		



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